

Claims

1. (Canceled)

2. (Currently amended) ~~The A semiconductor device according to Claim 1,~~
including a cooling system for controlling temperature of a refrigerant through a
heating section and a radiator, said semiconductor device being connected to and
cooled by said cooling system,

wherein a variation width ($\Delta T1$) of temperature controlled by said cooling
system through said heating section and said radiator is smaller than a
temperature variation ($\Delta T2$) of the refrigerant caused by variations in operating
conditions of said semiconductor device ($\Delta T1 < \Delta T2$); and

further comprising suppression means provided to cover an outer
periphery of said semiconductor device and suppressing transmission of heat
from an ambient atmosphere to said semiconductor device.

3. (Original) The semiconductor device according to Claim 2, wherein
said suppression means is a channel formed along all surfaces of a housing
covering the outer periphery of said semiconductor device and circulating the
refrigerant therethrough.

4. (Original) The semiconductor device according to Claim 2, wherein
said channel for cooling is provided inside said semiconductor device, and

electronic components constituting said semiconductor device are mounted on both sides of said channel.

5. (Original) The semiconductor device according to Claim 2, wherein said suppression means is a heat insulating portion provided to cover the outer periphery of said semiconductor device and made of a material having a small thermal conductivity.

6. (Original) The semiconductor device according to Claim 2, wherein said suppression means is a heat storage portion provided to cover the outer periphery of said semiconductor device.

7. (Original) The semiconductor device according to Claim 2, wherein said suppression means comprises a channel formed along at least two of outer peripheral surfaces of said semiconductor device and circulating the refrigerant therethrough; and

a heat insulating portion provided to cover the other outer peripheral surfaces of said semiconductor device and made of a material having a small thermal conductivity.

8. (Currently amended) The semiconductor device according to ~~Claim 1~~ Claim 2, wherein the refrigerant is water or a mixture prepared by mixing, to

water, at least one of alcohols, including ethylene glycol, propylene glycol and butylene glycol, and is used within the range of not lower than 70°C to lower than 100°C.

9-11. (Canceled)

12. (Currently amended) ~~The~~ A vehicular power conversion unit ~~according to Claim 11, mounted in a vehicle comprising an internal combustion engine and a motor,~~

said vehicular power conversion unit converting power supplied from a battery and controlling driving of said motor,

said vehicular power conversion unit being disposed, upstream of the internal combustion engine, in and cooled by a cooling system which cools said internal combustion engine by a refrigerant cooled by a cooling unit,

wherein said vehicular power conversion unit comprises:

a casing;

a cooling channel through which the refrigerant supplied from said cooling system flows;

a power conversion circuit module made up of a plurality of semiconductor chips and converting the power supplied from said battery; and

a conversion circuit control board made up of a plurality of electronic components and controlling driving of said semiconductor chips,

said casing containing said power conversion circuit module and said conversion circuit control board,

said vehicular power conversion unit being able to suppress heat transmission from the exterior such that a temperature variation width (ΔT_2) of the refrigerant depending on variations in operating conditions of at least said power conversion circuit module is larger than a variation width (ΔT_1) of temperature of the refrigerant controlled through said internal combustion engine and said cooling unit ($\Delta T_2 > \Delta T_1$); and

wherein said cooling channel is formed in said casing, and a heat insulating layer is formed in said casing by the refrigerant flowing through said cooling channel, thereby suppressing heat transmission from the exterior.

13. (Currently amended) The vehicular power conversion unit according to ~~Claim 11~~ Claim 12, wherein heat transmission from the exterior is suppressed by forming said casing of a material having a small thermal conductivity.

14. (Currently amended) The semiconductor device according to ~~Claim 1~~ Claim 2,

wherein the semiconductor device is connected to the cooling system so that the refrigerant flowed out of the radiator flows into the semiconductor device, and the refrigerant flowed out of the semiconductor device flows into the heating section.